

Product Summary

V_{BR} (min)	I_{PP} (max)	I_R (max)
28V	9.5A	100nA

Description

This new generation TVS is designed to protect sensitive electronics from the damage due to ESD. The combination of small size and high ESD surge capability makes it ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Applications

- Cellular Handsets
- Portable Electronics
- Computers and Peripheral

Features

- Low Profile Package (0.605mm max) and Ultra-small PCB Footprint Area (2.05 * 2.05mm max) Suitable for Compact Portable Electronics
- Provides ESD Protection per IEC 61000-4-2 Standard: Air $\pm 30kV$, Contact $\pm 30kV$
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: U-DFN2020-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.0065 grams (approximate)



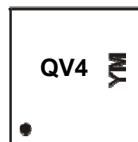
Device Schematic

Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
D26V0H1U2LP20-7	Standard	QV4	7	8	3,000/Tape & Reel

- Notes:
- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 - See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



QV4 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: B = 2014)
 M = Month (ex: 9 = September)

Date Code Key

Year	2013	2014	2015	2016	2017	2018	2019
Code	A	B	C	D	E	F	G

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	300	W	10/1000μs, Per Figure 1
Peak Pulse Current	I _{PP}	9.5	A	10/1000μs, Per Figure 1
ESD Protection – Contact Discharge	V _{ESD_Contact}	±30	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V _{ESD_Air}	±30	kV	IEC 61000-4-2 Standard

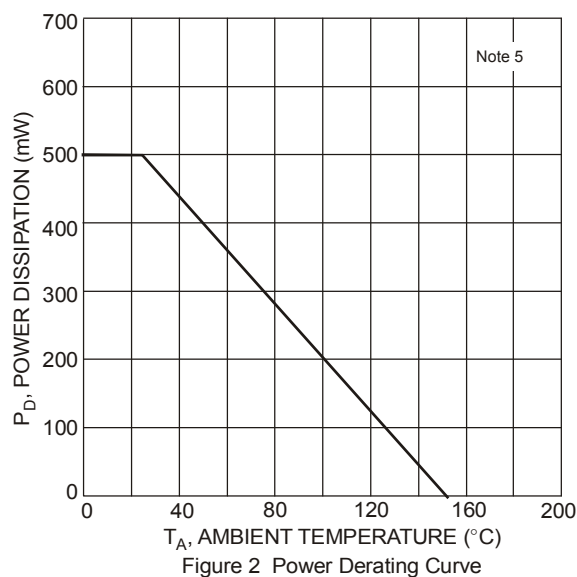
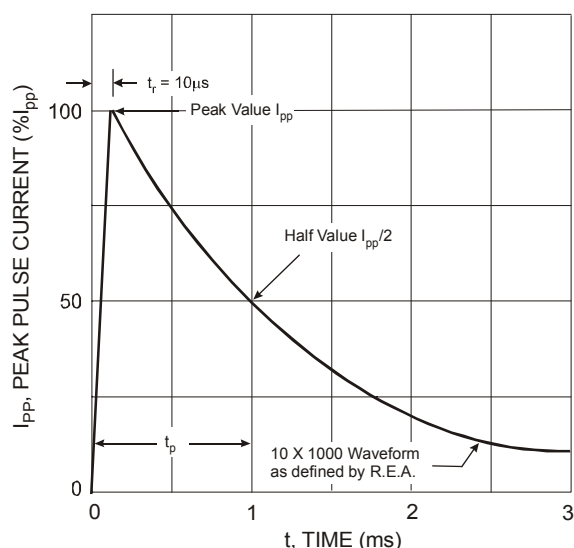
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P _D	500	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	250	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V _{RWM}	—	—	26	V	—
Channel Leakage Current (Note 6)	I _{RM}	—	—	100	nA	V _{RWM} = 26V
Forward Voltage	V _F	0.6	0.8	1.2	V	I _R = 10mA
Clamping Voltage	V _{CL}	—	—	40	V	I _{PP} = 9.5A, t _p = 10/1000μs
Breakdown Voltage	V _{BR}	28	—	31.9	V	I _R = 1mA
Channel Input Capacitance	C _T	—	630	—	pF	V _R = 0V, f = 1MHz

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
 6. Short duration pulse test used to minimize self-heating effect.



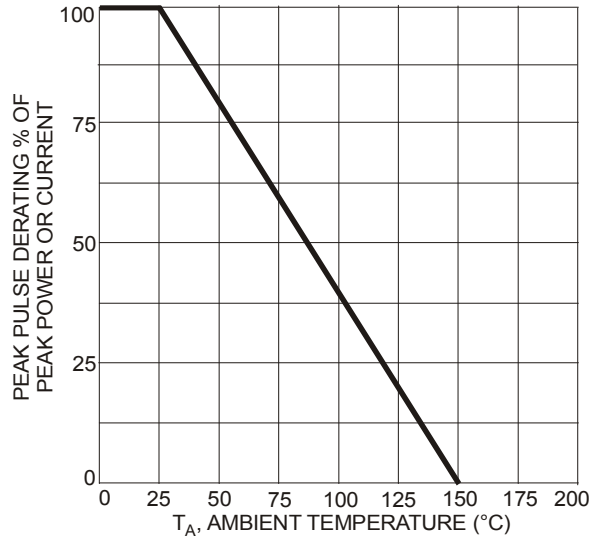


Figure 3 Power Dissipation vs. Ambient Temperature

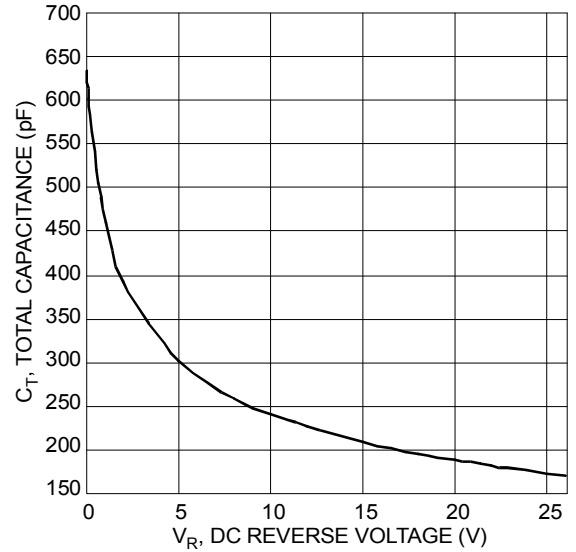


Figure 4 Typical Total Capacitance

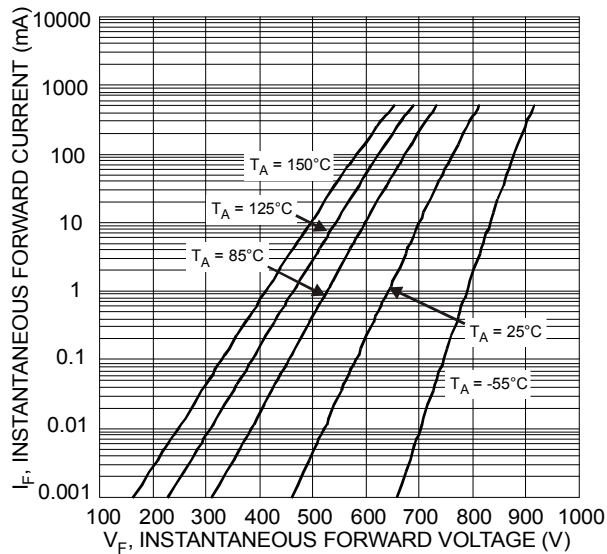


Figure 5 Typical Forward Characteristics

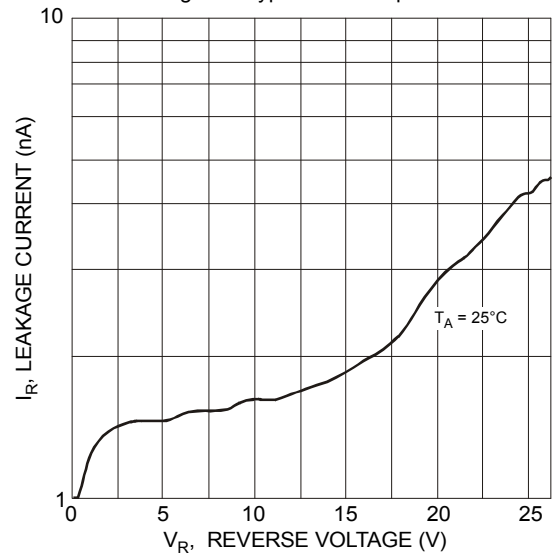
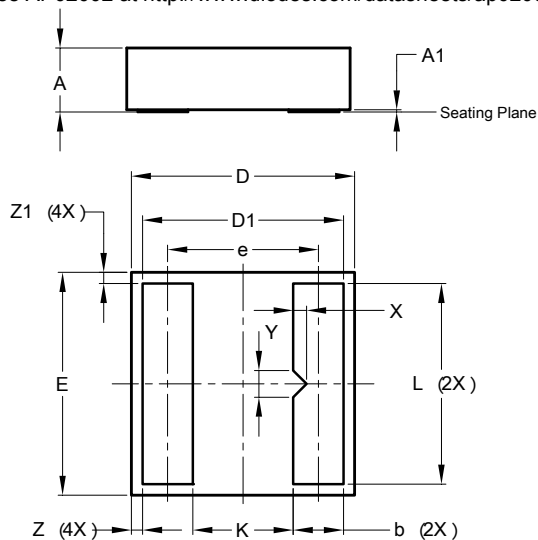


Figure 6 Typical Reverse Characteristics

Package Outline Dimensions

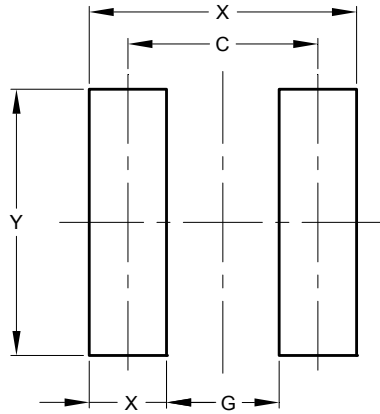
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



U-DFN2020-2			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0	0.05	0.02
b	0.35	0.55	0.45
D	1.90	2.10	2.00
D1	1.70	1.90	1.80
E	1.90	2.10	2.00
e	1.35 BSC		
K	0.80	1.00	0.90
L	1.70	1.90	1.80
X	-	-	0.120
Y	-	-	0.240
Z	0.10 BSC		
Z1	0.10 BSC		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	1.350
G	0.800
X	0.550
X1	1.900
Y	1.900

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